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# **Unpowered wireless transmission of ultrasound signals**

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#### Abstract

This paper presents a wireless ultrasound sensing system that uses frequency conversion to convert the ultrasound signal to a microwave signal and transmit it directly without digitization. Constructed from a few passive microwave components, the sensor is able to sense, modulate, and transmit the full waveform of ultrasound signals wirelessly without requiring any local power source. The principle of operation of the unpowered wireless ultrasound sensor is described first, and this is followed by a detailed description of the implementation of the sensor and the sensor interrogation unit using commercially available antennas and microwave components. Validation of the sensing system using an ultrasound pitch–catch system and the power analysis model of the system are also presented.

(Some figures in this article are in colour only in the electronic version)

# 1. Introduction

Damage detection based on ultrasound is one of the most popular and well-researched non-destructive inspection schemes employed by many structural health monitoring (SHM) systems (Giurgiutiu 2008, Staszewski et al 2003). In general, there are two ways to implement an ultrasound SHM system, namely the pulse-echo method or the pitchcatch method. The pulse-echo method excites an ultrasound wave and senses its echoes using a single ultrasound transducer (Cincotti et al 1999). Defects are detected as additional echoes created due to the discontinuities in the ultrasound propagation medium. The pulse-echo systems are simple and inexpensive to implement because it only needs the access to one location on the structure. On the other hand, the interrogation distance of the pulse-echo method is relatively shorter since sensing the echo requires the round-trip travel of the ultrasonic wave. The pitch-catch method uses two ultrasound transducers; one for excitation and one for sensing. Detection of surface and near-surface cracks using the pitchcatch method, in which the amplitude and frequency of the ultrasonic waves are influenced by the existence of damage, has been extensively studied (Kessler et al 2002, Ip and Mai 2004, Toutanji 2000). For ultrasound detection, optical fiberbased (Culshaw et al 2008, Li et al 2009, Fomitchov et al 2000) and piezoelectric wafer sensors (Giurgiutiu 2008) are among the most preferred sensors. Majority of the optical fiber ultrasound sensors reported in the literature are based on one of the following interferometric techniques: Mach–Zehnder, Michelson, Fabry–Perot or Sagnac interferometers; although these optical fiber techniques possess higher flexibility, high strength and heat resistance, they are relatively expensive, complicated to implement on-site and highly susceptible to temperature fluctuations (Chen *et al* 2004). On the other hand, the applications of the piezoelectric wafer sensors are quickly being extended because of their compactness, light weight, low cost, and wide frequency range.

Recently, ultrasound tomography systems have been successfully developed for damage mapping in complex structures (Hay *et al* 2006, Rajgopalan *et al* 2006, Prasad *et al* 2004). Ultrasound tomography usually requires the implementation of a transducer array. One transducer is excited at one time while the rest of the transducers are used to acquire the ultrasound signals. By rotating the exciting transducer, a large set of ultrasound signals can be collected. An image reconstruction algorithm can then be applied to map out the sources that reflect/diffract ultrasound waves. Obviously, the resolution of the ultrasound tomography system depends on the number of transducers available. However, due to practical limitations, the number of such sensors that can be attached to a structure is limited (Prasad *et al* 2004). Alternatively, a method of mechanically scanning contact transducers over the

entire surface was developed which utilizes fewer transducers (McKeon and Hinders 1999, Jansen et al 1990). Scanning tomography produced high spatial and image resolution, but the scanning hardware was too bulky and expensive. In addition, scanning with contact transducers is prone to errors from variations in coupling of the ultrasonic energy (Leonard et al 2002). To counter these coupling issues, air-coupled transducers that excite and receive guided waves at some liftoff from the test surface have been experimented (Popovics et al 2009, Wright et al 2005, Grandia and Fortunko 1995). However, the lift-off caused additional delays and attenuation, thus affecting the system performance. Ultrasound detection using an optical interferometer or a laser vibrometer is another non-contact ultrasound detection technique (Channels et al 2008, Murfin et al 2000, Huang et al 2008). Overall, noncontact ultrasound detection is very costly and less robust, making them more feasible for laboratory studies. Because of this reason, ultrasound SHM systems are still heavily relied on wired sensors. The weight penalty and maintenance concerns associated with wiring a large number of transducers have to be addressed for widespread field deployments of SHM systems.

Wireless sensors are attractive alternatives that can simplify the deployment of SHM systems and greatly reduce cable costs (Lynch and Loh 2006, Simonen et al 2004, Cho et al 2008). Furthermore, dense deployment of wireless sensors will increase the accuracy of the SHM techniques (Wu et al 2007, Caffrey et al 2004). The first wireless sensor for SHM was demonstrated by integrating wireless communications with accelerometers based on a low-power 8bit Motorola 68HC11 microcontroller (Stracer and Kiremidjian 1998). However, the processing power of these sensors was not sufficient to execute sophisticated processing algorithms. To boost up the performance, a dual microcontroller core was designed where one microcontroller performs the data collection and the other performs sophisticated engineering analysis (Lynch 2002). The Berkley Mote Mica and Mica 2 are among the other popular platforms, however, the data sampling rate of these sensors is quite limited (Nitta et al 2005). Despite the tremendous efforts on wireless sensor research, very few are related to wireless ultrasound sensors (Grosse et al 2008, Liu and Yuan 2008, Zhao et al 2008). A major limitation of wireless ultrasound sensing technology is the fundamental incompatibilities between the high frequency of the ultrasound signals and the limit data throughput of existing wireless transponders. For example, transmitting the full waveform of a 1 MHz ultrasound signal sampled at 10 samples per cycle with a 16-bit resolution would require the wireless transponder to transmit at a rate of 160 Mega-bits s<sup>-1</sup>. In contrast, the state-ofthe-art wireless sensor based on the IEEE 802.11g protocol can only transmit a maximum data rate of 30 Mega-bits  $s^{-1}$  (Vassis et al 2005). This is about five times lower than the desired transmission rate. Due to this limitation, existing wireless ultrasound sensors have to resort to on-board data processing and only transmit the feature information. However, ultrasound signal processing usually requires large computation and thus consumes lots of power, which could drain out the battery quickly if the microprocessor ran continuously.

This paper presents a wireless ultrasound sensor that is fundamentally different from mainstream wireless sensors.

Instead of having separate sensing, digitization, processing, and transmitting units, the present sensor uses frequency conversion to convert the ultrasound signal to a microwave signal and transmit it directly without digitization. More importantly, the frequency conversion and the transmission of the ultrasound-modulated signal can be achieved using a few passive microwave components. As a result, the sensor is able to sense, modulate, and transmit the full waveform of ultrasound signals wirelessly without requiring any local power source. The principle of operation of the sensor is explained first, followed by the discussions of the sensor design, sensor fabrication, and the derivation of the power-transmission model. Wireless transmission of the full waveform of ultrasound signals was demonstrated and characterized using an ultrasound pitch-catch system. The power-transmission model of the wireless ultrasound sensing system was experimentally validated.

## 2. Principle of operation

The wireless ultrasound sensing system is based on the principle of frequency conversion using a frequency mixer. A frequency mixer is a nonlinear microwave device that converts a high frequency, i.e. the RF frequency, to a low intermediate frequency, i.e. the IF frequency, and vice versa. A frequency mixer has three ports, the local oscillator (LO) port, the RF port, and the IF port. For the up-conversion operation, the input signals are the LO signal and the IF signal. The frequency of the output signal, i.e. the RF signal, is related to the frequencies of the LO and the IF signals as

$$f_{\rm RF} = f_{\rm LO} \pm f_{\rm IF}.\tag{1}$$

For the down-conversion operation, the frequency mixer takes the RF signal and the LO signal as the inputs and produces an IF signal with a frequency of

$$f_{\rm IF} = f_{\rm RF} \pm f_{\rm LO}.$$
 (2)

Because ultrasound waves in general have frequencies of a few tens of kilohertz to a few megahertz, direct wireless transmission of the ultrasound signals would require an antenna so big that makes it impractical to be implemented at the sensor level. In this application, we use a passive frequency mixer to up-convert the ultrasound signal to the microwave frequency so that it can be transmitted wirelessly using a compact antenna. Once the wireless signal is received, the ultrasound signal can be down-converted back to its original frequency.

An illustration of the wireless ultrasound sensing system is shown in figure 1. It consists of two major subsystems; the wireless sensor node and the sensor interrogation unit (SIU) located at a distance away from the sensor. The sensor node consists of four components, namely two antennas (sensor Rx and Tx), a frequency mixer, and a piezo wafer sensor. The antennas and the frequency mixer form a wireless transponder that up-converts the ultrasound signal to a microwave signal and transmits the ultrasound-modulated microwave signal wirelessly. The piezo wafer sensor converts the mechanical



Figure 1. Unpowered wireless ultrasound sensor and associated sensor interrogation unit.

ultrasound motion to an electrical signal  $f_{\rm U}$ . To up-convert the ultrasound signal to the microwave frequency, an interrogation microwave signal  $f_i$ , i.e. the LO signal, is received by the sensor Rx antenna. Mixing the ultrasound signal and the LO signal using the frequency mixer produces an ultrasoundmodulated microwave signal  $f_i \pm f_U$ . This modulated signal, encoded with the ultrasound information, is transmitted using the sensor Tx antenna. Since all components at the sensor level are passive, i.e. they do not need a local power supply, unpowered wireless transmission of the ultrasound signal is thus achieved. The SIU broadcasts the microwave interrogation signal  $f_i$  to the sensor node and demodulates the received signal  $f_{\rm i} \pm f_{\rm U}$  to recover the ultrasound signal  $f_{\rm U}$ . It consists of two antennas (SIU Rx and Tx), a signal generator, and a signal demodulation system. The microwave signal generated by the signal generator is split into two signals using a directional coupler. One part of the signal serves as the LO signal for the down-converting mixer. The other part of the signal, serving as the interrogation signal  $f_i$ , is amplified by a power amplifier, broadcasted through the SIU Tx antenna, and received by the sensor Rx antenna. The ultrasoundmodulated signal  $f_{\rm i} \pm f_{\rm U}$  is received by the SIU Rx antenna and passed on to the signal demodulation system to recover the ultrasound signal. The signal demodulation system first filters the received signal using a bandpass filter (BPF), amplifies the received modulated signal using a low-noise amplifier (LNA), and down-converts it using the frequency mixer. Since the LO signal has the same frequency as the interrogation signal, the IF port of the down-converting mixer produces a signal with frequency components at  $f_{\rm U}$  and  $2f_{\rm i} \pm f_{\rm U}$ . Filtering this IF signal using a low pass filter (LPF) recovers the ultrasound signal  $f_{\rm U}$ . After filtering, the ultrasound signal can be amplified again and acquired using a conventional wired data acquisition system.

#### **3.** Design and fabrication of the wireless transponder

The wireless transponder at the sensor node was constructed by soldering two 0 dBi chip antennas (Antenna Factor ANT-2.4-Chp-x, 6.6 mm long, 2.3 mm wide, and 1mm thick) and a frequency mixer (Minicircuits, ZX05-73L-S+) on a printed circuit board (Roger 4350B, 0.5 mm thick, and 50 mm × 25 mm). The layout of the transponder board, designed using an Electromagnetic Simulation Tool, Sonnet Pro, is shown in figure 2(a). The two chip antennas were designed to have a 90° polarization differences to reduce the cross-talk between these two antennas. The board material is a laminate with a dielectric substrate sandwiched between two thin copper coatings (12.7  $\mu$ m thick). One side of the copper coating was milled using a CNC machine to produce the copper traces, which serve as the microstrip transmission lines that electrically connect the two chip antennas and the mixer. The width of the copper trace was calculated from its characteristic impedance  $z_0$ , the dielectric constant of the substrate material  $\varepsilon$ , the height of the substrate h, and the copper thickness t as

$$w = \frac{7.4625 h}{e^{(Z_0\sqrt{0.475\varepsilon + 0.67/60})}} - 1.25t.$$
 (3)

For a substrate thickness of 483  $\mu$ m, a copper thickness of 12.7  $\mu$ m, a dielectric constant of 3.66, and a characteristic impedance of 50  $\Omega$ , the trace width is calculated to be 1 mm. The traces are chamfered at an angle of 45°, at all perpendicular turns, to maintain a characteristic impedance of 50 ohms throughout the length. For shielding purpose, the copper coating besides the copper traces are connected to the copper coating on the back side of the substrate, i.e. the ground plane, by drilling a few holes on the laminate and filling the holes with solder (see figure 2(b)). The distance between the microstrip traces and the ground plane is not very crucial. A rule of thumb is to keep this distance approximately equal to (or greater than) the trace width. A larger gap will reduce the shielding efficiency. According to the antenna manufacturer's instructions, the area underneath the chip antennas should be free of any components, traces or planes. Therefore, the copper coatings on both sides of the laminate that are underneath the chip antenna were etched off. After the board was machined, the chip antennas and the frequency mixer were soldered on the microstrip traces.



Figure 2. Wireless transponder; (a) front view with chip antennas and mixer mounted on the traces; (b) back view showing the ground plane.



Figure 3. Wireless ultrasound sensing system.



Figure 4. Signal demodulation system.

# 4. Hardware implementation and experiment setup

The implementation of the passive wireless ultrasound sensing system is shown in figure 3. An ultrasound pitch–catch system was implemented on an aluminum channel by installing two piezo wafer sensors; one for actuation and the other for sensing. The wall thickness of the aluminum channel is 2 mm. The two piezo wafer sensors (APC 850, 7 mm in length and width, 250  $\mu$ m in thickness) were placed at a distance of 279 mm apart. A 5.5 cycle tone-burst signal with peak-topeak amplitude of 10 V was generated by a signal generator (Agilent 33250A) and supplied directly to the piezo wafer actuator to excite Lamb waves. Two wideband 8 dBi log periodic antennas (Hyperlink Technologies, HG2458-08LP) were aligned to have the same polarization as their counterpart antennas at the sensor node. The distance between the SIU and the sensor was 0.6 m.

The SIU signal demodulation system was assembled using commercially available components shown in figure 4.

A directional coupler (Minicircuits, ZABDC20-322H-S+) separates the microwave signal supplied by a signal generator (Agilent, E4421B) into two signals. The large signal from the 'output' port was connected to the LO port of the downconverting mixer (Minicircuits, ZX05-73L-S+). The small signal output from the 'CPL out' port was amplified using two power amplifiers (Minicircuits, ZX60-6013E-S+ and ZVA-213-S+) to reach a power level of around 24 dBm. This amplified microwave signal, serving as the interrogation signal  $f_i$ , was supplied to the SIU Tx antenna and broadcasted to the wireless sensor node. The ultrasound-modulated microwave signal, received by the SIU Rx antenna, was first bandpassfiltered (Minicircuits, VBFZ-2575-S+), amplified using a LNA (Minicircuits, ZRL-2400LN+), and finally supplied to the RF port of the down-converting mixer. The demodulated ultrasound signal, i.e. the IF output of the mixer, was filtered using a low pass filter (Minicircuits, VLF-1000+) and amplified using a pre-amplifier (Physics Acoustics Corporation 2/4/6 preamplifier). Finally, the output of the pre-amplifier was acquired using a high speed oscilloscope (LeCory SDA 760Zi).



**Figure 5.** Comparison of wired and wirelessly acquired ultrasound signals at 400 kHz excitation frequency; (a) acquired signals; (b) normalized frequency spectra of the first arriving wavepackets; (c) wireless versus wired signal at different excitation frequencies; (d) ratio between peak values of wired and wirelessly acquired signals at different excitation frequencies.

## 5. Power-transmission model

Assuming the sensor Rx antenna is placed at a distance d from the SIU Tx antenna, the power of the signal received by the sensor Rx antenna can be calculated from the Friis transmission equation (Balanis 2005) as

$$P_{\rm s} = \frac{P_{\rm i}G_h G_{\rm s}\lambda^2}{(4\pi d)^2},\tag{4}$$

where  $P_i$  is the interrogation power,  $G_h$  and  $G_s$  are the gains of the SIU Tx and sensor Rx antennas, and  $\lambda$  is the microwave wavelength. Denoting the root-mean-square (RMS) amplitude of the output of the piezo wafer sensor as  $V_U$ , the RMS amplitude of the ultrasound-modulated signal is

$$V_{\rm m} = V_{\rm s} V_{\rm U} = \sqrt{P_{\rm s} R} V_{\rm U} = \sqrt{P_{\rm i} G_h G_{\rm s} R} \frac{\lambda}{4\pi d} V_{\rm U} \qquad (5)$$

where *R* is the impedance of the frequency mixer and  $V_s$  is the RMS amplitude of the microwave signal received by the sensor node. The power of the ultrasound-modulated signal, taking the insertion loss of the mixer  $A_{mixer1}$  into consideration, is

$$P_{\rm m} = A_{\rm mixer1} \left( \frac{V_{\rm m}^2}{R} \right) = \frac{A_{\rm mixer1} P_{\rm i} G_h G_s \lambda^2}{(4\pi d)^2} V_{\rm U}^2.$$
(6)

The power of the modulated signal  $P_r$ , received by the SIU Rx antenna, is again calculated from the Friis transmission equation as

$$P_{\rm r} = \frac{P_{\rm m}G_hG_s\lambda^2}{(4\pi d)^2} = \frac{A_{\rm mixer1}P_{\rm i}(G_hG_s)^2\lambda^4}{(4\pi d)^4}V_{\rm U}^2.$$
 (7)

Denoting the gain of the LNA as  $A_{LNA}$  and the gain of the pre-amplifier as  $A_{amp}$ , the RMS amplitude of the recovered ultrasound signal is

$$V_{\rm r} = \sqrt{A_{\rm amp} P_{\rm IF} R} = \sqrt{A_{\rm amp} A_{\rm LNA} A_{\rm mixer1} A_{\rm mixer2} P_{\rm i} P_{\rm LO}} \\ \times \frac{G_h G_{\rm s} \lambda^2}{(4\pi d)^2} R V_{\rm U}, \tag{8}$$

where  $A_{\text{mixer2}}$  is the insertion loss of the down-converting mixer and  $P_{\text{LO}}$  is the power of the LO signal.

## 6. Experimental results and analysis

Wireless transmission of the full waveform of ultrasound signals was demonstrated and characterized using the ultrasound pitch-catch system shown in figure 3. The interrogation signal had a frequency of 2.4 GHz and the power output of the signal generator was 5 dBm. The ultrasound excitation signal was a 5.5 cycle Hanning windowed toneburst signal with a peak-to-peak amplitude of 10 V and a repetition period of 10 ms. The ultrasound signals acquired by the oscilloscope was averaged over 100 sweeps. For an excitation burst frequency of 400 kHz, the comparison between the signals collected through the wireless channel and the wired piezo sensor wafer are shown in figure 5. With a preamplifier gain of 40 dB, the signal collected using the wireless means has a similar amplitude as that of the ultrasound signal directly acquired from the piezo wafer sensor. The wired signal shown in figure 5(a) has a  $180^{\circ}$  phase difference from the as-acquired wired signal. This phase difference and the slight time delay between the wired and wireless signals are due to the pre-amplifier. The first arriving wavepackets were extracted from the signals using a rectangular window between

| Measurands                                     | Supplied (dBm) | Calculated (dBm) | Measured (dBm) |
|--|----------------|------------------|----------------|
| Interrogation signal ( <i>P</i> <sub>i</sub> ) | 24.43          |                  |                |
| Sensor received signal $(P_s)$                 |                | -3.32            | -4.5           |
| Ultrasound signal $(P_{\rm U})$                | -20            |                  |                |
| Ultrasound-modulated signal $(P_m)$            |                | -37.5            | -36.5          |
| SIU received modulated signal $(P_r)$          |                | -64.4            | -62.9          |
| Signal amplified by LNA                        |                | -37.9            | -37.9          |
| Down-converting LO signal $(P_{LO})$           | 3.45           |                  |                |
| Recovered ultrasound signal $(P_{ru})$         |                | -47.5            | -50            |

 Table 1. Comparison of calculated and measured signal power at different stages. (Note: measurement data compensated for cable/connector loss.)

50 and 70  $\mu$ s. By performing fast Fourier transformation (FFT) on the first arriving wavepackets, we can compare the signal-to-noise ratio (SNR) of these two sets of data. As shown in figure 5(b), the two signals have almost identical frequency spectra except the wireless signal has a small bulge around 100 kHz. We have also compared the peak value of the 1st arriving wavepacket at different excitation frequencies. The wireless signal matched relatively well with the wired signal, as shown in figure 5(c). Between 200 and 300 kHz, the ultrasound waveform was not very well defined and the amplitude was very low. These may be the reason that the ratio between the peak amplitude of the wireless and wired signal is slightly lower at these frequencies than those at other frequencies. Overall, the wireless ultrasound sensing system has a relatively flat bandwidth (see figure 5(d)).

In order to validate the power-transmission model, the wireless transponder was assembled using discrete components, i.e. two prototype chip antennas and a packaged frequency mixer (see figure 6). These components were connected through SMA connectors so that step-to-step power measurements can be carried out. A 500 kHz continuous sinusoidal signal with a power of -20 dBm, equivalent to a 20 mV RMS amplitude for a 50  $\Omega$  impedance, was generated by a signal generator and supplied to the IF port of the sensor mixer to imitate the ultrasound signal. Again the signal generator was set at a frequency of 2.4 GHz and a power level of 5 dBm, which resulted in an interrogation signal of 24.43 dBm and an LO signal of 3.45 dBm for the SIU mixer. The signal power was measured from the spectra of the signals acquired by the high speed oscilloscope sampled at 20 Giga samples per second. The power measurements have an uncertainty of 2.7 dB for the microwave signals and 0.6 dB for the ultrasound signal, due to the cable and connector loss. The measurement data were therefore increased by the corresponding amount to compensate for these losses. The measured and calculated signal powers at different stages differed by a few decibels, which is likely contributed by the uncertainties of the cable/connector losses (see table 1). The main loss is contributed by the wireless transmission of the interrogation signal and the ultrasound-modulated signal. Each path contributed about -28 dB of loss at a distance of 0.6 m between the two antennas. To reduce these losses, high gain antennas, such as patch antennas for the sensor node and a dual-polarized horn antenna for the SIU, can be used. Increasing the gains of the antennas and the interrogation power will enable wireless interrogation of the ultrasound

![](_page_6_Figure_6.jpeg)

Figure 6. Wireless transponder with discrete components.

sensor at a larger distance. The insertion losses of the mixers appear to be insignificant, even though the sensor mixer was operating at a LO signal that was way below the specified level. Compared with the wireless transponder with discrete components, the wireless transponder constructed on the PCB has an additional 10 dB loss. Better design and fabrication of the board can reduce this loss.

## 7. Conclusions

We have demonstrated an unpowered wireless ultrasound sensor based on the principle of frequency conversion. The design and implementation of the wireless ultrasound sensor are presented and the performance of the wireless ultrasound sensing system was characterized. A power-transmission model for this system was established and validated.

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